RELIABILITY REPORT FOR

MAX8640Y/ZEXT24+

MAX8640ZEXT24+

PLASTIC ENCAPSULATED DEVICES

February 10, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX8640Y/ZEXT24+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX8640Y/MAX8640Z step-down converters are optimized for applications where small size, high efficiency, and low output ripple are priorities. They utilize a proprietary PWM control scheme that optimizes the switching frequency for high efficiency with small external components and maintains low output ripple voltage at all loads. The MAX8640Z switches at up to 4MHz to allow a tiny 1µH inductor and 2.2µF output capacitor. The MAX8640Y switches at up to 2MHz for higher efficiency while still allowing small 2.2µH and 4.7µF components. Output current is guaranteed up to 500mA, while typical quiescent current is 28µA. Factory-preset output voltages from 0.8V to 2.5V eliminate external feedback components. Internal synchronous rectification greatly improves efficiency and replaces the external Schottky diode required in conventional step-down converters. Internal fast soft-start eliminates inrush current so as to reduce input capacitor requirements. The MAX8640Y/MAX8640Z are available in the tiny 6-pin, SC70 (2.0mm x 2.1mm) and µDFN (1.5mm x 1.0mm) packages. Both packages are lead-free.

II. Manufacturing Information

A. Description/Function:	Tiny 500mA, 4MHz/2MHz Synchronous Step-Down DC-DC Converters
B. Process:	S4
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	Carsem Malaysia, UTL Thailand
F. Date of Initial Production:	August 18, 2006

III. Packaging Information

A. Package Type:	6-pin SC70
B. Lead Frame:	Cu Alloy
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non Conductive Epoxy
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	326°C/W
K. Single Layer Theta Jc:	115°C/W

IV. Die Information

A. Dimensions:	32 X 31 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 44 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 24.4 \times 10^{-9}$

$\lambda = 24.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the S4 Process results in a FIT Rate of 4.6 @ 25C and 79.2 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PN82 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-200 mA.

Table 1
Reliability Evaluation Test Results

MAX8640Y/ZEXT24+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	44	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data